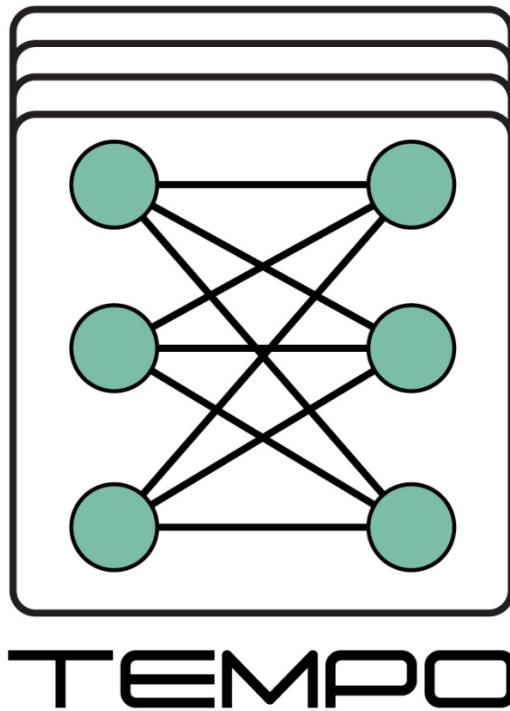


# Technology & Hardware for nEuromorphic coMPuting

- ECSEL Research and Innovation Actions (RIA\*) –



## Deliverable 2.3 – Report on OxRAM integration –

<b>Work Package</b>	WP N° 2 – Emerging Technologies
<b>Document Date</b>	23 January 2020
<b>Revision N°</b>	1
<b>Status</b>	FINAL
<b>Dissemination Level</b>	Confidential
<b>Responsible Partner</b>	CEA
<b>Name</b>	Elisa Vianello
<b>Contact Information</b>	elisa.vianello@cea.fr

© Copyright 2019 TEMPO Project. All rights reserved

This document and its contents are the property of the TEMPO Partners. All rights relevant to this document are determined by the applicable laws. This document is furnished on the following conditions: no right or license in respect to this document or its content is given or waived in supplying this document to you. This document or its contents are not be used or treated in any manner inconsistent with the rights or interests of TEMPO Partners or to its detriment and are not be disclosed to others without prior written consent from TEMPO Partners. Each TEMPO Partner may use this document according to the TEMPO Consortium Agreement.



\* This project has received funding from the ECSEL Joint Undertaking (JU) under grant agreement No 826655. The JU receives support from the European Union's Horizon 2020 research and innovation programme and Belgium, France, Germany, Netherlands, Switzerland".





## Publishable Summary

One of the main objectives of the Work Package 2, *Emerging Technologies*, is to address all the required process and technology developments for OxRAM memories and to address the required adjustments of them for neuromorphic hardware. This deliverable presents the technology developments realised to enable the OxRAM memories integration into STM 28FDSOI technology (300 mm wafers) between Metal 5 and Metal 6. First, the process flow is presented. Second, the critical process steps for the OxRAM integration, realised on demonstrator or simplified short loops, are presented.